



2022 ANNUAL RESULTS PRESENTATION

1st March 2023

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ASMP enabling the digital world

Group Key Highlights

Key Highlights

Unique, Broad-based Portfolio Mitigates Impact of Macroeconomic Environment & Semiconductor Downcycle

Q4 Revenue Exceeds Guidance
Gross Margin Above 40% for 7 Quarters

SMT – Stellar Performance

Automotive – Record Revenue

Advanced Packaging – Packing A Punch

Becoming An ESG Leader In Semiconductor Industry

Reduce Scope 1 and Scope 2 emissions to net-zero by 2035

- Part of comprehensive ASMPT Net-Zero emissions roadmap

Leadership-Level Founding Member of inaugural Semiconductor Climate Consortium (“SCC”)

- SCC Members jointly address climate change across entire semiconductor value chain
- Help accelerate solutions to climate problems through pooling of industry resources



FY 2022 Key Financials

Second-highest Revenue and Bookings¹ after Super-cycle Year 2021



Revenue

US\$2,473M
(-11.8% YoY)²



Bookings

US\$2,356M
(-29.4% YoY)²



Backlog

US\$1,152M
(-10.7% YoY)²



Gross Margin

41.1%
(+55 bps YoY)



Operating Margin

16.7%
(-216 bps YoY)



Net Profit

HK\$2,618M
(-17.5% YoY)



EPS

HK\$6.36
(-17.6% YoY)



DPS

HK\$3.20
(-17.9% YoY)



Notes:

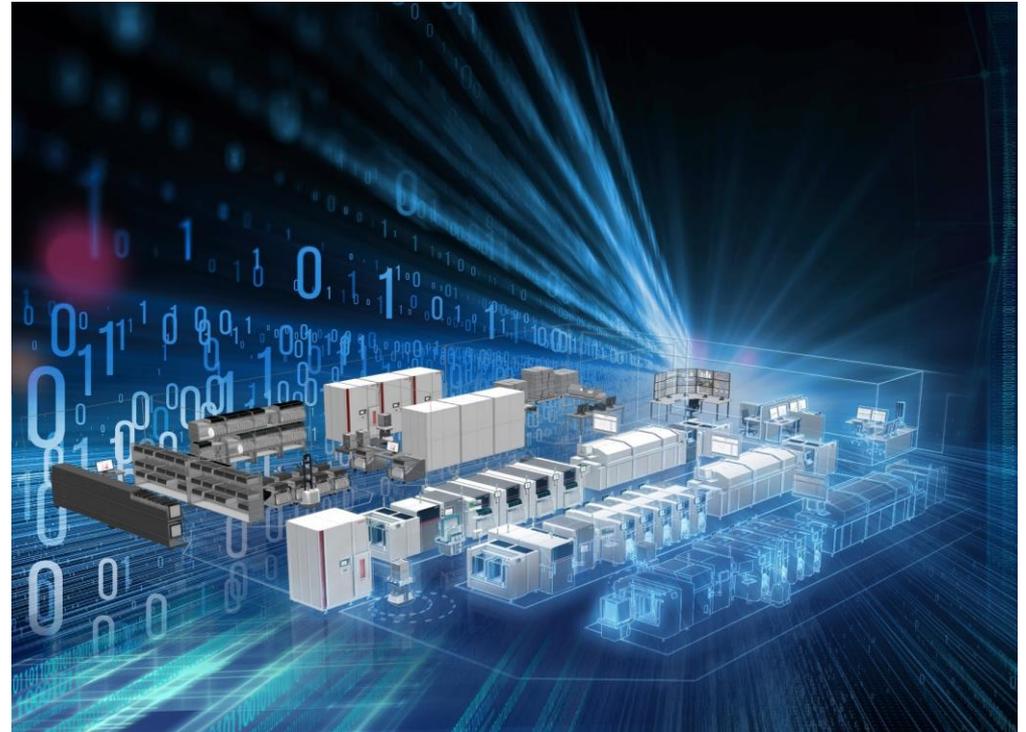
¹ Excludes contribution from Materials business, which has been deconsolidated and equity accounted for since 29 December 2020

² The YoY % comparison is based on financials denominated in HK\$

SMT – Stellar Performance

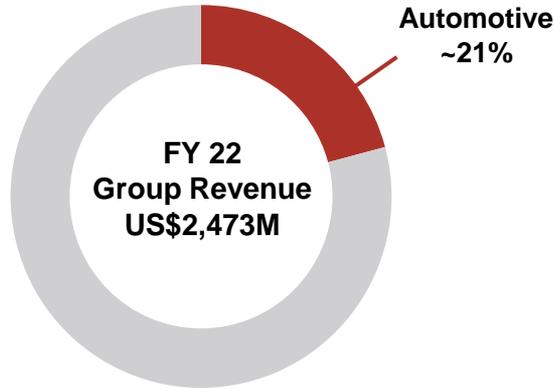
Breaking Records in 2022

- Record annual revenue in 2022
- Strong demand for its high-end placement and printing tools
- Automotive and Industrial end markets contributed ~50% of 2022 segment's revenue
- Market share surpassed competitors



Automotive – Record Revenue

Comprehensive Range of Solutions Gains Traction



- Addressable market to grow from approx. US\$2.0 billion in 2023 to US\$2.9 billion in 2027, at CAGR of ~10%
- Strong momentum with YoY revenue growth of ~20%
- Laser singulation and sintering solutions are process of record (“POR”) for Silicon Carbide related applications

Laser Singulation & Silver Sintering Solutions



Power Module

Advanced Packaging Solutions



Self-Drive Computing Board

Automotive CIS Solutions



Vehicle LiDAR Module



LED / Advanced Display Solutions



In-Vehicle Micro LED Display

Die/Wire Bond & Mold



Power Discrete Packages
Analog, Logic, MCUs

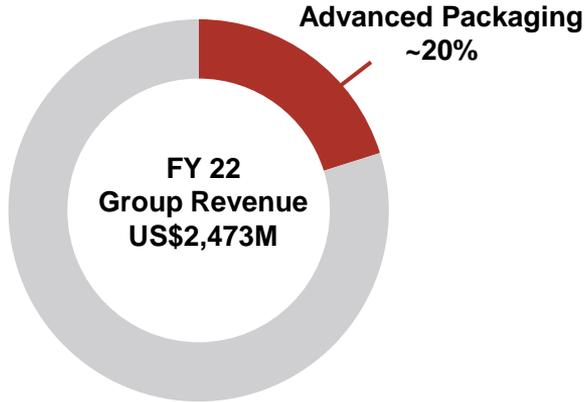
SMT Solutions



Automotive PCB

Advanced Packaging – Packing A Punch

Steady Contribution to Group Revenue



Addressable market to grow from approx. US\$1.5 billion in 2023 to US\$2.5 billion in 2027, at CAGR of ~13%

Leading position:

- TCB – Broadening Logic customer base; inroads into memory market
- Panel ECD and SiP – Dominant market share

Other growth areas: Advanced Displays, Laser Singulation, Silicon Photonics

Comprehensive Advanced Packaging Solutions

Advanced Packaging Processes	Physical Vapor Deposition	Electro-Chemical Deposition – Wafer/Panel Lvl Plating	Laser Singulation	Wafer/ Panel Lvl Fan Out	Ultra Precision Die Bonding (Silicon Photonics)	Mass Transfer (Mini/Micro LED)	Multi-Chip Module Bonding	Thermo Compression Bonding	Flip Chip	Wafer Level Fan In	SMT SiP Placement	Hybrid Bonding
ASMPT Solutions												
	Apollo Series Conductor	Stratus Series	Laser 1205	NUCLEUS	NANO	AD300 Series	VECTOR	FIREBIRD	AD8312FC	SUNBIRD	SIPLACE TX Micron	LithoBolt

Thermo-Compression Bonding (“TCB”)

- Strong progress on next-gen TCB tools with ultra-fine pitch, environmentally friendlier, chip-to-wafer capabilities
- Address TCO challenges in domains served by nascent Hybrid Bonding technology
- Well-placed to meet longer term structural growth for heightened HI requirements
- High accuracy $<1\mu\text{m}$



Panel Level (“PL”) ECD

- Driven primarily by High Performance Computing (“HPC”) needs
- Multiple tools in several High-Volume Manufacturing (“HVM”) sites worldwide
- Well placed to meet growing need for PL Packaging, HI packaging plating and $<10\mu\text{m}$ line/space capabilities



SMT System-in-Package

- Driven by 5G, smartphones and high-end wearables
- New chip assembly solution to be rolled out within 2023 for high speed + accuracy die placement tools



Advanced Displays

- 'Fungibility' between mass transfer and mass bonding capabilities
- Mini-LED solutions speeding up mass market penetration for advanced displays
- Micro-LED primed to meet HVM needs



Laser Singulation

- A growing POR replacing conventional blade dicing processes
- High accuracy ($<1.5\mu\text{m}$)
- Long term revenue \geq US\$100 million annually



Silicon Photonics (“SiPh”)

- Highest placement accuracy in class ($\pm 0.2\mu\text{m}$)
- Suitable for both SiPh and Co-Packaged Optic device manufacturing needs
- Utilised by leading tier-one players for optical communication



FY 2022 Group Financial Results



2nd Highest Ever Revenue and Bookings¹
Resilient Gross Margin Performance

Revenue

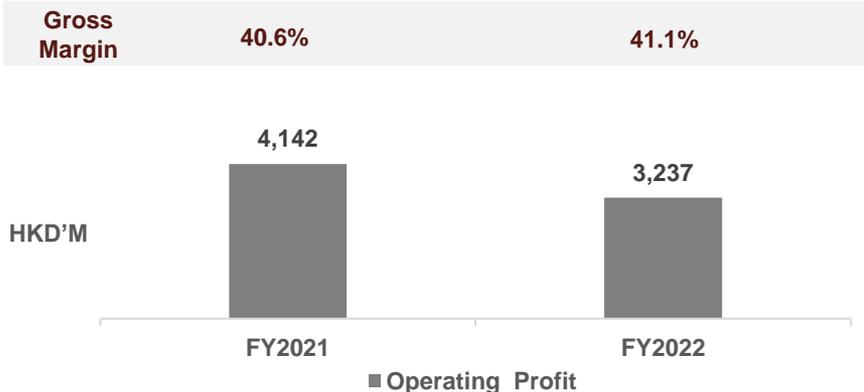
- Highest revenue contribution from Automotive

Bookings

- Declined YoY due to high base effect
- AP, Automotive and Industrial contributed ~60% of bookings

Gross margin

- Improvement driven by both SEMI and SMT due to a favourable product mix, targeted pricing adjustments and ongoing strategic initiatives



Operating Margin

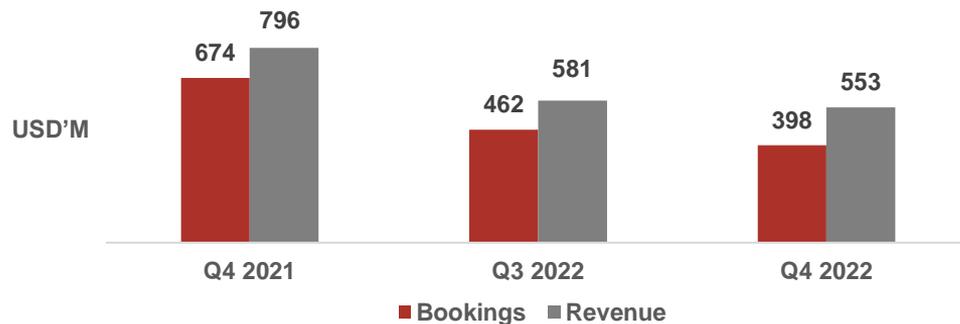
18.9%

16.7%

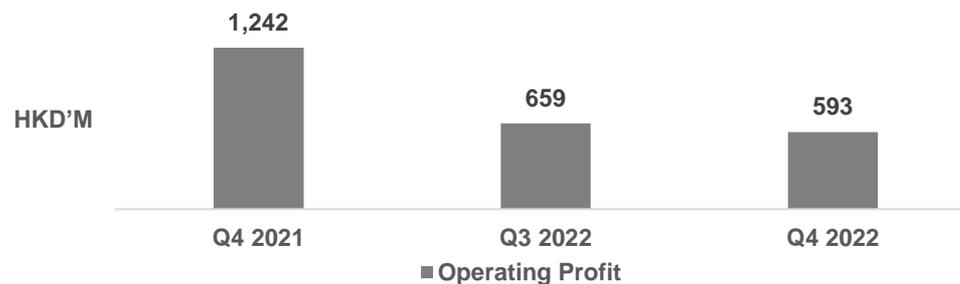
Note:

¹ Excludes contribution from Materials business, which has been deconsolidated and equity accounted for since 29 December 2020

Q4 2022 Group Financial Results



Quarter	Gross Margin
Q4 2021	41.3%
Q3 2022	40.9%
Q4 2022	41.4%



Quarter	Operating Margin
Q4 2021	20.0%
Q3 2022	14.4%
Q4 2022	13.7%

Revenue Above Guidance 7th Consecutive Quarter of Gross Margin >40%

Revenue

- Exceeded top end of Q4 revenue guidance
- Strong YoY growth from SMT mitigated SEMI's decline

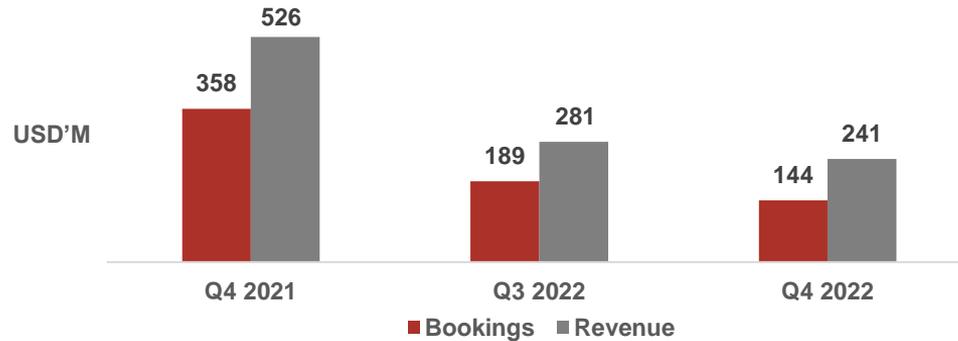
Bookings

- Declined YoY due to high base effect and QoQ due to seasonality

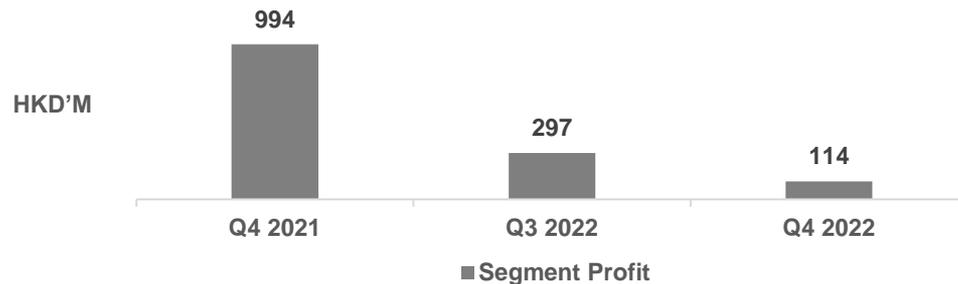
Gross margin

- Above 40% even in downcycle

Q4 2022 Semiconductor Solutions Segment Performance



Period	Gross Margin
Q4 2021	43.7%
Q3 2022	44.6%
Q4 2022	44.4%



Period	Segment Margin
Q4 2021	24.3%
Q3 2022	13.5%
Q4 2022	6.1%

Positive YoY Gross Margin Growth

Revenue

- IC/Discrete: Weak demand for mainstream bonders but tools serving Automotive and AP largely increased QoQ
- Optoelectronics: Driven by demand for ultra-fine pitch Mini LED displays and Silicon Photonics
- CIS: Continued weakness in smartphone market

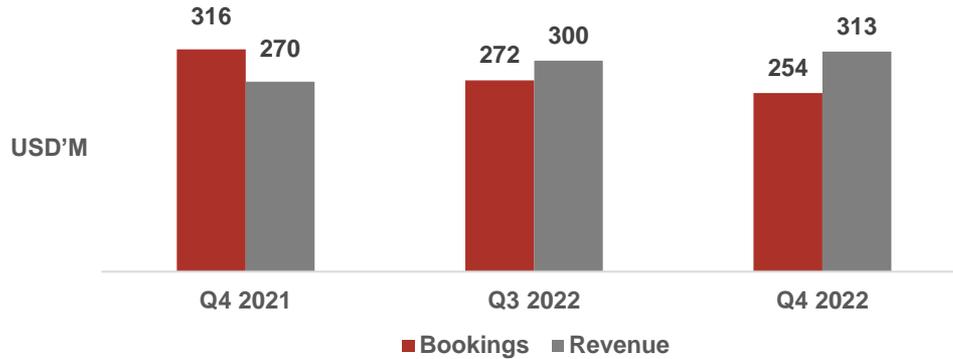
Bookings declined:

- Declined YoY due to high base effect and QoQ due to ongoing semiconductor downcycle and seasonality

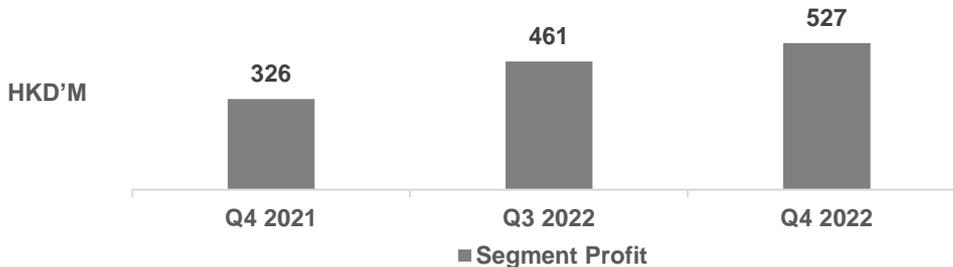
Gross margin

- YoY improvement due to increased revenue contributions from Automotive and AP and cost control measures

Q4 2022 SMT Solutions Segment Performance



Period	Gross Margin
Q4 2021	36.7%
Q3 2022	37.4%
Q4 2022	39.1%



Period	Segment Margin
Q4 2021	15.5%
Q3 2022	19.6%
Q4 2022	21.5%

Robust YoY and QoQ performance

Revenue

- Industrial and Automotive contributed >50% of segment's revenue

Bookings

- Declined YoY and QoQ due to seasonality and continued weakness in Consumer, Communication and Computers
- Strong contributions from Industrial and Automotive

Gross margin

- YoY and QoQ improvement due to a favourable product mix

Key End-Market Applications

Serving Broad-based End-Market Applications*

Automotive	Consumer	Communication	Industrial	Computers	Others
 <p>Visual Sensors Infotainment LIDAR Sensors V2X communications Entertainment Platforms</p>	 <p>TV Wearables Audio devices Video devices Gaming consoles Other Consumers</p>	 <p>Mobile Phones Wired Infrastructure Wireless 5G Communications Infrastructure</p>	 <p>EV Charging Smart Factories Smart Offices Other Industrial</p>	 <p>Personal Computers Servers Datacentres HPC Other Computers</p>	 <p>Medical Devices Aerospace Others**</p>

FY 2022
Revenue

~21%

~19%

~16%

~16%

~10%

~18%

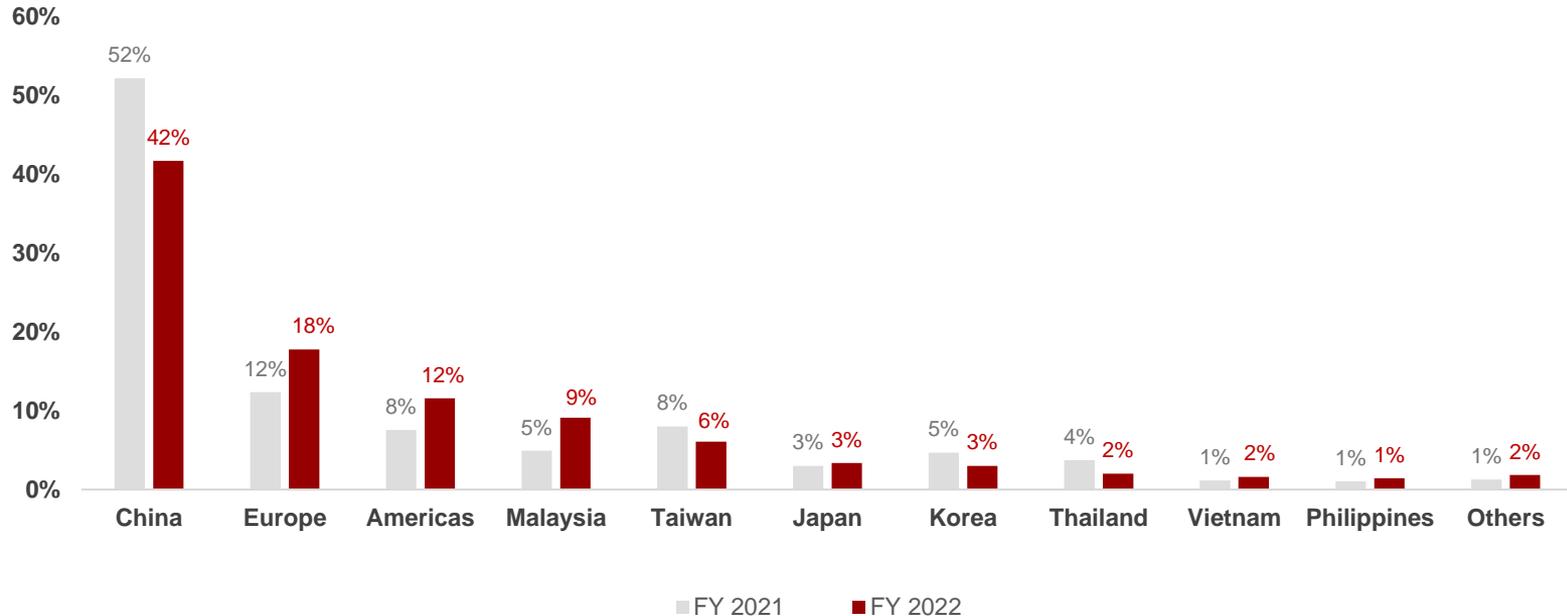
*Revenue mix is based on management's best estimates.

**Others include revenue from spares, services and other applications that cannot be meaningfully identified.

Key Partner to Industry Leading Customers

Serving Industry-Leading Semiconductor and Electronics Manufacturers Globally

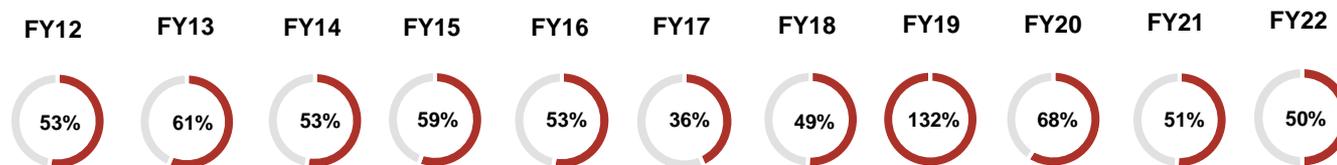
Revenue Contribution by Geography



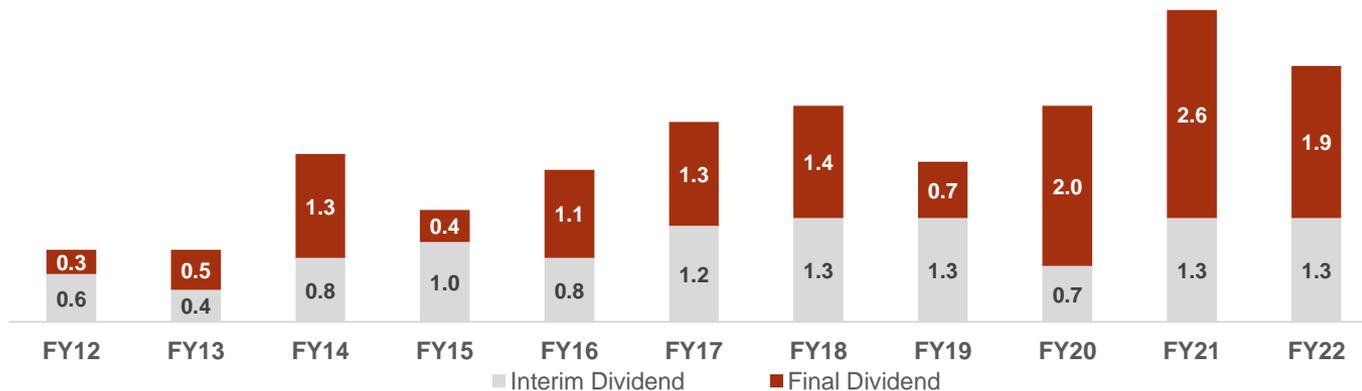
Returning To Shareholders

Consistent Dividend Payout Ratio Policy Supported by Healthy Cash Flow

Dividend Payout (%)



Dividend Per Share (HKD)



Dividend policy of consistent annual dividend payout of around 50%
(consistent with average dividend payout ratio 2012-2022)



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digital world

Q1 2023 Revenue Guidance

Q1 2023 Revenue Guidance

US\$455m to US\$525m

(-27.4% YoY and -11.4% QoQ at mid-point of guidance)

Affected by ongoing semiconductor downcycle and macroeconomic uncertainties

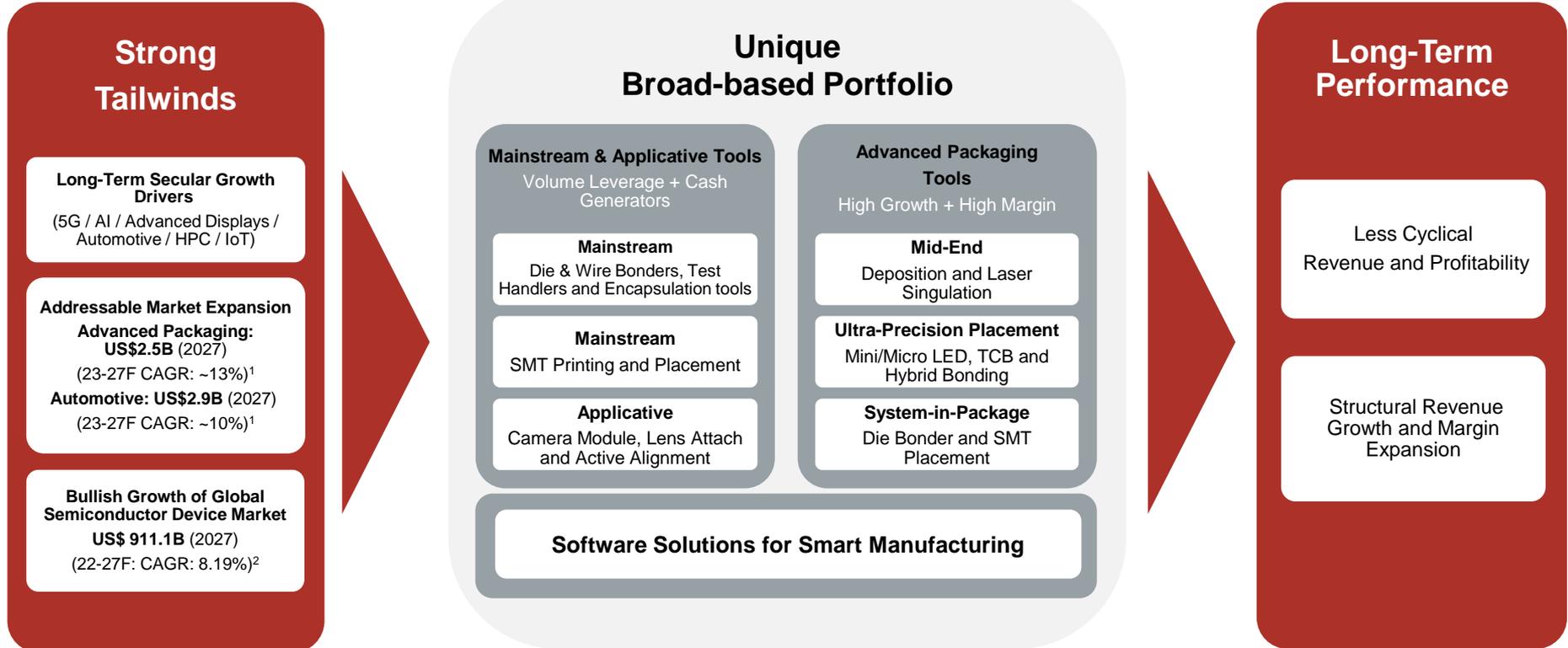
2023 Prospects

- Market consensus that semiconductor sector recovery could begin in 2H 2023
- Group's business performance in 2023 will be supported by:
 - Sizeable order backlog
 - Strength in Automotive, Industrial and AP markets
 - Unique broad-based portfolio

Key Investor Takeaways

Key Investor Takeaways

Unique Broad-based Portfolio

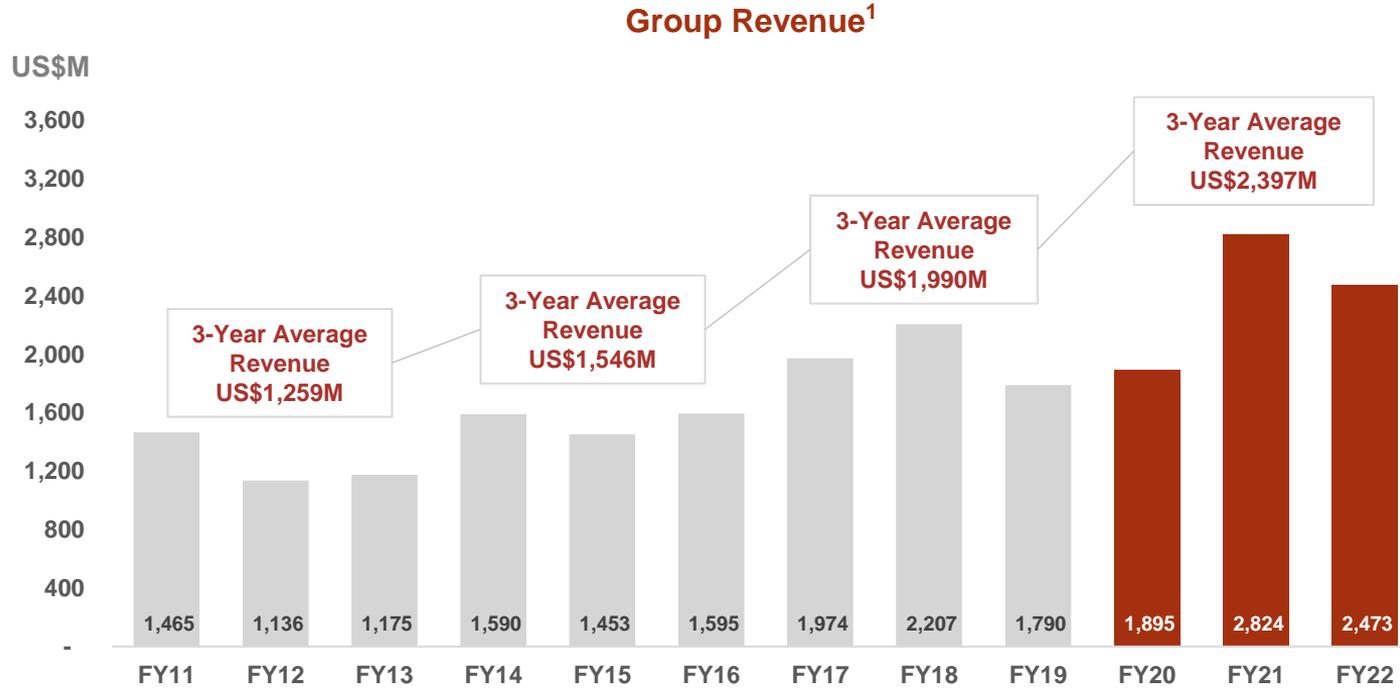


¹ Company Management's Estimates

² Mordor Intelligence

Key Investor Takeaways

Through-cycle Industry Revenue Growth



Note:

¹ Excludes contribution from Materials business, which has been deconsolidated and equity accounted for since 29 December 2020

Q&A

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Thank You!

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